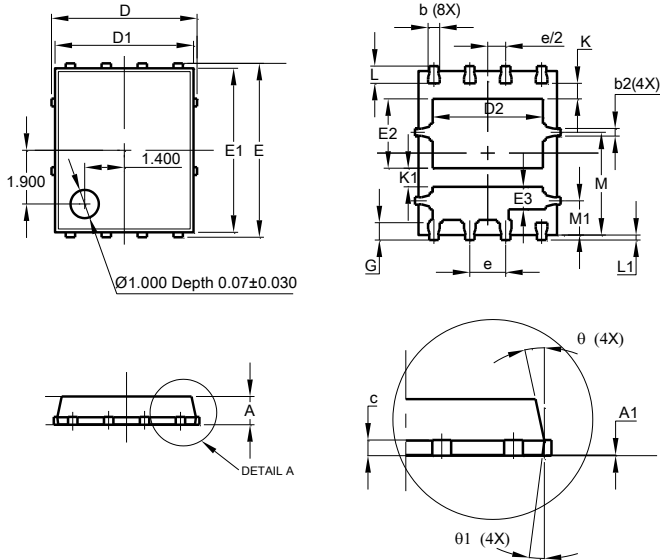


**Package Outline Dimensions**

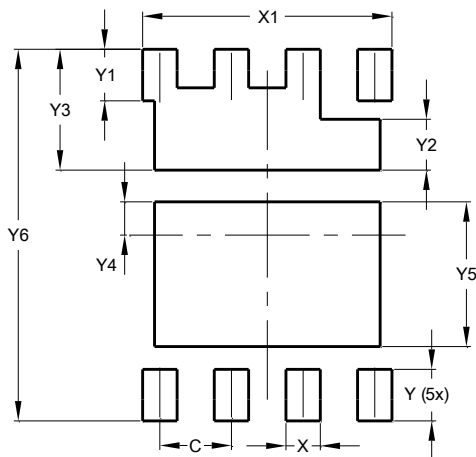
**PowerDI5060-8 (Type B)**



PowerDI5060-8 (Type B)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	—
b	0.33	0.51	0.41
b2	0.20	0.40	0.273
c	0.230	0.330	0.273
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.50	4.40	3.90
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	2.25	2.65	2.45
E3	0.595	0.995	0.795
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	—	—
K1	0.51	—	—
L	0.51	0.71	0.61
L1	0.05	0.20	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
θ1	10°	12°	11°
θ2	6°	8°	7°
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

**PowerDI5060-8 (Type B)**



Dimensions	Value (in mm)
C	1.270
X	0.610
X1	4.420
Y	0.910
Y1	0.910
Y2	0.895
Y3	2.130
Y4	0.585
Y5	2.550
Y6	6.550

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.